

Solder Termination Sleeve FTLV

FTLV NT/HT

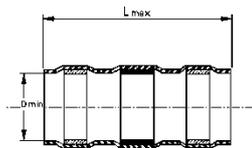
Shrinking solder joints with internal solder ring and thermoplastic sealing rings.

Application:

Reliable insulated electrical solder connection in one single operation, reproducible quality and inspectability. Low shrink temperature enables application on temperature sensitive insulation (e.g. PVC). Used for shield termination and wire splicing.

Continuous operating temperature: FTLV NT: -55°C up to +105°C / FTLV HT: -55°C up to +150°C

Shrinking temperature: Min. +115°C



| Description | Inner diameter D (mm) | | Length L (mm) |
|-------------|-----------------------|-----------------|---------------|
| | As supplied | Fully recovered | |
| FTLV-1 | 2,4 | 0,9 | 15,8 |
| FTLV-2 | 3,2 | 1,4 | 15,8 |
| FTLV-3 | 5,0 | 2,5 | 15,8 |
| FTLV-4 | 6,3 | 3,2 | 19,0 |
| FTLV-5 | 7,6 | 4,0 | 19,0 |
| FTLV-6 | 11,7 | 5,7 | 28,0 |
| FTLV-7 | 13,8 | 6,0 | 28,0 |

Spezial sizes on request

Packaging: Plastic bags of 100 pcs. respectively 200 pcs.

Ordering description: 200 pcs. FTLV-NT 2

Please advise if you would like to order solder sleeves for low temperatures (NT) or for high temperatures (HT)

Solder Termination Sleeve FTLV

FTLV NT/HT

| Properties | | Typical value |
|------------|-------------------------------------|--------------------|
| Mechanical | Tensile strength | 6,7 MPa min. |
| Thermal | Flammability | Self extinguishing |
| Electrical | Dielectrical strength | 2 kV/mm min. |
| Chemical | Copper corrosion (16 Std. at 121°C) | Non-corrosive |

Processing instructions:

Processing of the solder termination sleeves should be carried out with hot air equipment (e.g. HG3000 SLE). To ensure proper heating we recommend reflectors (e.g. HG3000 RFL L1-9 for solder joints up to 9mm diameter). The soldering connector is positioned above the point to be soldered and heated by hot air. As a result, the insulation shrinks onto the conductor diameter and the solder tin flows.

Please do not hesitate contacting us for further information.